



**DEFENSE LOGISTICS AGENCY**  
 LAND AND MARITIME  
 POST OFFICE BOX 3990  
 COLUMBUS, OH 43218-3990

April 4, 2019

Mr. John McIntosh  
 U.S. Circuits, Inc.  
 2071 Wineridge Place  
 Escondido, CA 92029

RE: Notification of Qualification; MIL-PRF-31032/1, /2; FSC 5998; CAGE Code 66483;  
 VQ(VQE-19-033743); CN 066976

Dear Mr. McIntosh:

Qualification of your products is granted under the current issue of the specification as a result of successful qualification testing to Military Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032/1 and /2. The capabilities qualified for the base material and slash sheet indicated below shall be listed on Qualified Manufacturers List QML-31032 and Qualified Product List QPL-55110. The effective date of these qualifications is April 4, 2019.

<p>MANUFACTURER</p> <p>U.S. Circuits, Inc.          2071 Wineridge Place          Escondido, CA 92029</p>	<p>PLANT LOCATIONS</p> <p>Same Address as Manufacturer</p>	<p>CAGE CODE: 66483</p> <p>PHONE #: (760) 489-1413</p> <p>EMAIL:  <a href="mailto:jmcintosh@uscircuit.com">jmcintosh@uscircuit.com</a></p>
<p>Specification: MIL-PRF-31032/1, MIL-PRF-31032/2          Qualification Letters: VQ(VQE-19-033743)          Composition: H - Homogenous thermoplastic base material printed boards          Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant          Max. Panel Size: 18" x 24"          Max. Number of Layers: 10          Max. Board Thickness: .110"          Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating          Aspect Ratio: 9:1 Through-Hole          Min. Conductor Width/Space: .004"/.004"          Hole Preparation: Plasma Etchback          Hole Wall Conductive Coating: Graphite Based Direct Metallization          Copper Plating: Reverse Pulse Plate          Solder Resist: Liquid Photoimageable          Finish System: HASL</p>		

Test report number 31032-5324-19 has been assigned to your test data. These qualifications are based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Keith Powell at [vqe.kp@dla.mil](mailto:vqe.kp@dla.mil) or 614-692-9508.

DLA Land and Maritime-VQE requires all correspondences be submitted in electronic format. Examples of this include requests for technical evaluations, qualification and status reports, retention test data and requests for testing authorization (including test plans). In the event that a specific report or document is very large size (>15 MB) please submit the information via the following website, <https://safe.amrdec.army.mil/safe/Welcome.aspx> . This website can be used to transmit up to 25 files totaling up to 2GB of data. When using SAFE, please zip your documents into 1 or 2 zip files to reduce the number of files transmitted. Electronic documents are a more efficient format and will help our office evaluate your questions or testing data in a more efficient and expeditious manner.

Sincerely,

for ROBERT M. HEBER  
Chief  
Sourcing and Qualifications Division



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 2071 Wineridge Place  
 Escondido, CA 92029

RE: Notification of Qualification; MIL-PRF-31032/1, /2; FSC 5998; CAGE Code 66483;  
 VQ(VQE-19-033744); CN 066977

Dear Mr. McIntosh:

Qualification of your products is granted under the current issue of the specification as a result of successful qualification testing to Military Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032/1 and /2. The capabilities qualified for the base material and slash sheet indicated below shall be listed on Qualified Manufacturers List QML-31032 and Qualified Product List QPL-55110. The effective date of these qualifications is April 4, 2019.

<p>MANUFACTURER</p> <p>U.S. Circuits, Inc.          2071 Wineridge Place          Escondido, CA 92029</p>	<p>PLANT LOCATIONS</p> <p>Same Address as Manufacturer</p>	<p>CAGE CODE: 66483</p> <p>PHONE #: (760) 489-1413</p> <p>EMAIL:  <a href="mailto:jmcintosh@uscircuit.com">jmcintosh@uscircuit.com</a></p>
<p>Specification: MIL-PRF-31032/1, MIL-PRF-31032/2          Qualification Letters: VQ(VQE-19-033744)          Composition: H - Homogenous thermoplastic base material printed boards          Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant          Max. Panel Size: 18" x 24"          Max. Number of Layers: 10          Max. Board Thickness: .110"          Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating          Aspect Ratio: 9:1 Through-Hole          Min. Conductor Width/Space: .004"/.004"          Hole Preparation: Plasma Etchback          Hole Wall Conductive Coating: Graphite Based Direct Metallization          Copper Plating: Reverse Pulse Plate          Solder Resist: Liquid Photoimageable          Finish System: HASL</p>		

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